

Description

The HSX044N25 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent R_{DS(ON)} and gate charge for most of the synchronous buck converter applications.

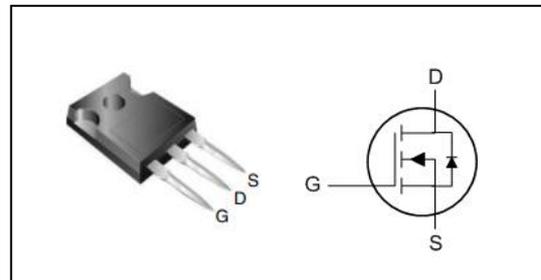
The HSX044N25 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- Super Low Gate Charge
- Green Device Available
- Excellent Cdv/dt effect decline
- Advanced high cell density Trench technology

Product Summary

V _{DS}	250	V
R _{DS(ON),max}	44	mΩ
I _D	55	A

TO-247 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	250	V
V _{GS}	Gate-Source Voltage	± 20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	55	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	35	A
I _{DM}	Pulsed Drain Current ²	195	A
EAS	Single Pulse Avalanche Energy ³	165	mJ
P _D @T _C =25°C	Total Power Dissipation ³	350	W
T _{STG}	Storage Temperature Range	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	45	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	0.4	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	250	---	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =5A	---	34	44	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	3	---	5	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =150V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =150V, V _{GS} =0V, T _J =125°C	---	---	100	
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ± 20V, V _{DS} =0V	---	---	± 100	nA
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =20A	---	75	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	1.5	---	Ω
Q _g	Total Gate Charge (10V)	V _{DS} =50V, V _{GS} =10V, I _D =40A	---	155	---	nC
Q _{gs}	Gate-Source Charge		---	23	---	
Q _{gd}	Gate-Drain Charge		---	45	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =50V, V _{GS} =10V, R _G =3.3Ω I _D =40A	---	33	---	ns
T _r	Rise Time		---	8.2	---	
T _{d(off)}	Turn-Off Delay Time		---	65	---	
T _f	Fall Time		---	6	---	
C _{iss}	Input Capacitance	V _{DS} =50V, V _{GS} =0V, f=1MHz	---	8547	---	pF
C _{oss}	Output Capacitance		---	429	---	
C _{rss}	Reverse Transfer Capacitance		---	85	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,5}	V _G =V _D =0V, Force Current	---	---	55	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =20A, T _J =25°C	---	---	1.2	V
t _{rr}	Reverse Recovery Time	I _F =40A, dI/dt=100A/μs,	---	157	---	nS
Q _{rr}	Reverse Recovery Charge	T _J =25°C	---	1073	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V_{DD}=40V, V_{GS}=10V, L=0.5mH, R_g=25Ω
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.



Typical Characteristics

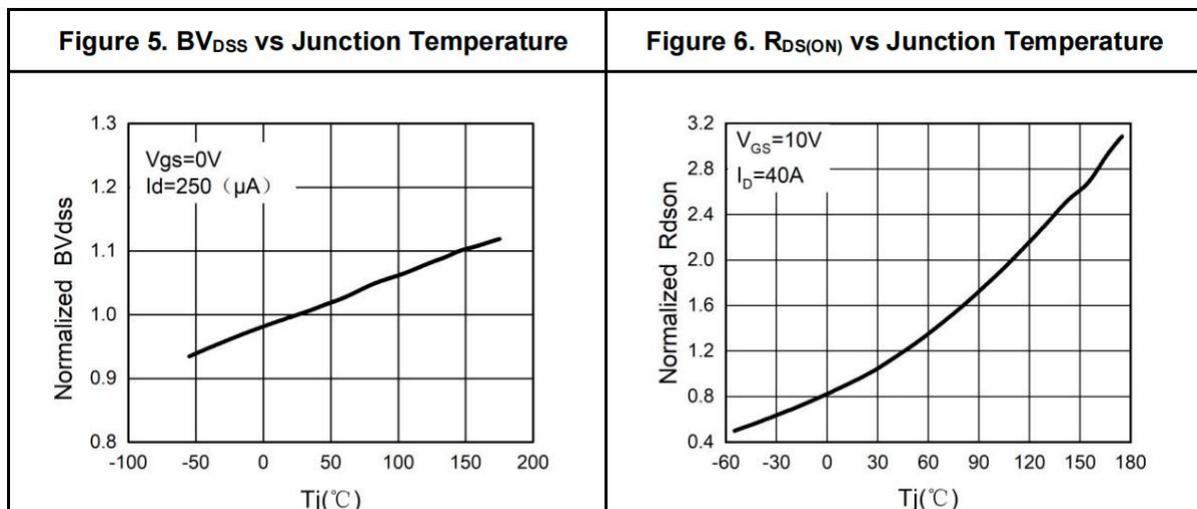
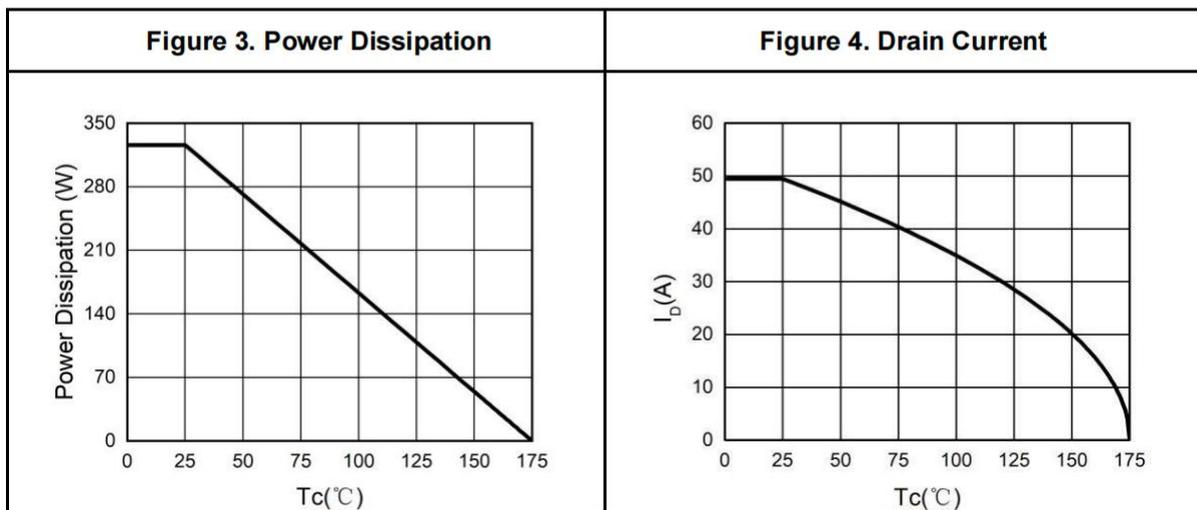
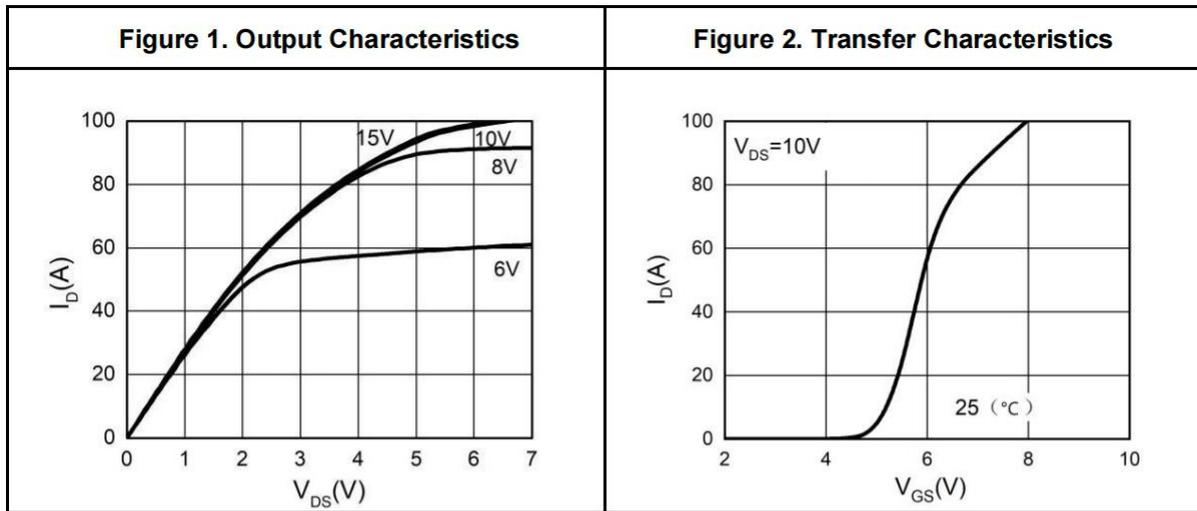




Figure 7. Gate Charge Waveforms

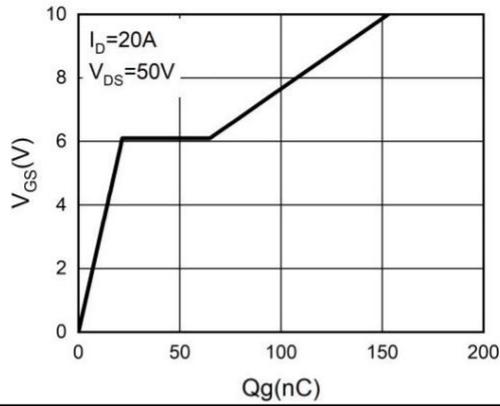


Figure 8. Capacitance

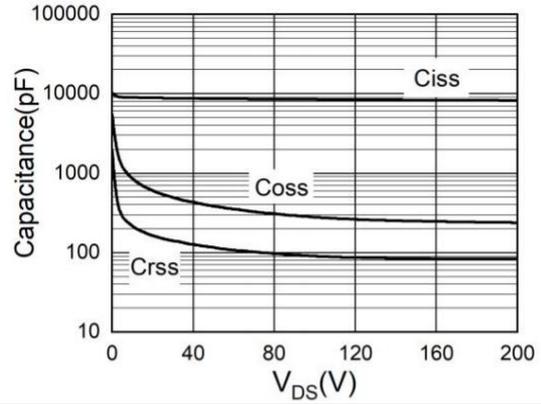


Figure 9. Body-Diode Characteristics

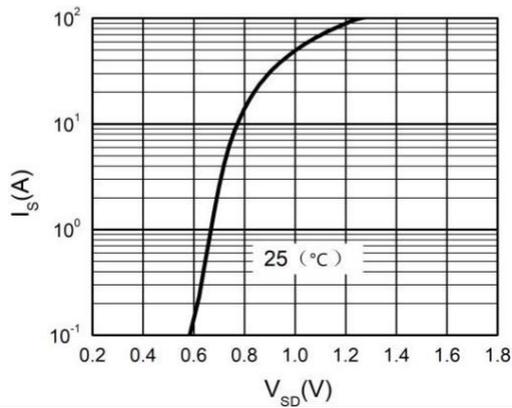


Figure 10. Maximum Safe Operating Area

